

PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	ANALOG MEMS SENSORS/26/16483	
1.3 Title of PCI	Change of Main Die Identification on Product Box PQ Label for Previous NXP Sensor Product	
1.4 Product Category	Pls refer to the impacted (NXP) products list.	
1.5 Issue date	2026-07-09	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	SCHAEFER MARC
2.1.2 Phone	+49 89460062136
2.1.3 Email	marc.schaefer@st.com
2.2 Change responsibility	
2.2.1 Product Manager	David MONK, Simone FERRI
2.1.2 Marketing Manager	Marc OSAJDA
2.1.3 Quality Manager	Sixto ARJONILLA

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General (Logistic)	Delivery Note, Labels, Certificate of Conformity	ASECL, ATKL

4. Description of change

	Old	New
4.1 Description	PQ Box Label uses ASIC die as MAIN die	PQ Box Label uses MEMS die as MAIN die
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change

5.1 Motivation	Change in information of PQ Box Label
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Transition period; starting in August 2026 and finalized in March 2027
-----------------	--

7. Timing / schedule

7.1 Date of qualification results	2026-07-01
7.2 Intended start of delivery	2026-08-03
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

16483 Public product.pdf
16483 PCI_Change of Main Die Identification on Product Box PQ Label_GM.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	FXLS8964AFR3	
	FXLS8974CFR3	
	FXPS7550A4ST1	
	MPL115A2ST1	
	MPL3115A2ST1	
	NBP8FD4ST1	
	NTM88H135ST1	
	NTM88H135T1	
	NTM88K135ST1	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCI Title : Change of Main Die Identification on Product Box PQ Label for Previous NXP Sensor Product

PCI Reference : ANALOG MEMS SENSORS/26/16483

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

NTM88K155ST1	NTM88H125ST1	NXLS96422AESR2
NXLS96322AESR2	NXLS95630AESR2	NXLS96230AESR2
NXLS95120AESR2	FXPS71407ST1	NXLS95722AESR2
NXLS95333AESR2	NXLS96433AESR2	NXLS96220AESR2
FXPS71407BPST1	NXLS95230AESR2	NXLS95433AESR2
NTM88J135ST1	NXLS95620AESR2	NXLS96421AESR2
NXLS96620AESR2	NXLS95733AESR2	NXLS96333AESR2
FXPS7550DI4ST1	NXLS96120AESR2	FXPS7140P7ST1
NXLS95130AESR2	NXLS95220AESR2	NXLS95422AESR2
NXLS96733AESR2	NXLS95322AESR2	NXLS96722AESR2
FXLS8961AFR1	FXLS8964AFR3	FXLS8967AFR3
FXPS7250DS4ST1	NXLS96130AESR2	FXPS7115DI4ST1
FXPS7115DS4ST1	MPL3150A2ST1	FXLS8974CFR3
FXPS7550A4ST1	NBP8FD4ST1	NTM88H145ST1
FXLS8971CFR1	FXPS7250DI4ST1	FXPS7550DS4ST1
FXPS7400A4ST1	NTM88J125ST1	NTM88H135ST1
NTM88J145ST1	NTM88K145ST1	NTM88H155ST1
MPL3115A2ST1	FXPS7250A4ST1	FXPS7165DI4ST1
NTM88K135ST1	FXPS7400DI4ST1	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved



PCI Change of Main Die Identification on Product Box PQ Label for Previous NXP Sensor Product

June 24, 2026

Background

- For a multi-chip product with an ASIC and a MEMS, STM identifies a Main die and a Secondary Die.
- STM will be making a change to the Main die identification for previous NXP Sensors' products.
- The Main die identifies:
 - The Country of Diffusion as noted on shipping labels.
 - The Lot Information as noted on the shipping labels.
- Current: ASIC die identified as the Main die.
- Future: MEMS die identified as the Main die.
- Reason for Change:
 - The MEMS die defines the primary function of the product. The MAIN die will be updated to reflect this primary function.
- Implementation Date:
 - The projected implementation date will include a transition period; beginning in August 2026 and finalized by end of March 2027.



Label Change

- The Main die change will impact the label on **ALL** Products with 2 die in the package.
- The **LOT** noted on the label will now be associated with the MEMS lot ID.
- The **Country of Diffusion** will be associated with the MEMS die.
 - Previous ASIC:
 - USA (ATMC or TSMC11) or
 - China (TSMC10) or
 - Taiwan (TSMC3).
 - New MEMS:
 - Italy (STMA) or
 - Canada (DALSA) or
 - USA (OHT).

Country of Diffusion →

LOT →

Example



Our technology starts with You



Find out more at www.st.com

© STMicroelectronics - All rights reserved.

ST logo is a trademark or a registered trademark of STMicroelectronics International NV or its affiliates in the EU and/or other countries.

For additional information about ST trademarks, please refer to www.st.com/trademarks.

All other product or service names are the property of their respective owners.

